



EMVCo Security Evaluation

Development / Production Site Attestation Letter

Please accept this document as confirmation of the EMVCo Security Evaluation Process.

Attestation Reference Number: SALN0109

Company: Goldpac Limited

Address: Goldpac Tech Park
4088 Jinfeng Rd, Fengshan
Guangdong Province
Zhuhai 519070 People's Republic of China

Site Name: Goldpac R&D Center

Site Address: 15F, Parkview Place, No.2 East 4th, Ring Road
Chaoyang District
Beijing, 100016 People's Republic of China

Type: Development

Date Issued: 19 Sep 2025

SAR Reference: ESVGOL003_SAR_M0.pdf

Security Laboratory: Applus+

Certification Reference Documents:

- EMVCo Security Evaluation Process, v5.4, July 2024
- EMVCo Development and Production Site Audit Guidelines, v1.1, May 2015

Authorized by: Alan Mushing
Security Evaluation Working Group Chair
EMVCo, LLC

Date: 19 Nov 2025

The EMVCo Security Evaluation Process is intended to provide with valuable and practical information relating to the general security performance characteristics and the suitability of use for smart card related products and IC chip-based tokens. The EMVCo Security Evaluation Process is designed to ensure a robust security foundation for these products at the product family and component level. The full terms and conditions upon which EMVCo Attestation Letters are issued by EMVCo are contained in the EMVCo Security Evaluation Process Document and the EMVCo Security Evaluation Certification Contract. The Product Provider, when distributing this EMVCo Attestation Letter, shall deliver it in its entirety.